



| Parameter | Ratings | Units |
|---------------------|---------|----------------------|
| Blocking Voltage | 350 | V_P |
| Load Current | 100 | mA_{rms} / mA_{DC} |
| On-Resistance (max) | 50 | Ω |

Features

- 3750V_{rms} Input/Output Isolation
- Low Drive Power Requirements (TTL/CMOS Compatible)
- High Reliability
- Arc-Free With No Snubbing Circuits
- FCC Compatible
- VDE Compatible
- No EMI/RFI Generation
- Small 8-Pin Package
- Machine Insertable, Wave Solderable
- Surface Mount, Tape & Reel Version Available

Applications

- Telecommunications
 - Telecom Switching
 - Tip/Ring Circuits
 - Modem Switching (Laptop, Notebook, Pocket Size)
 - Hook Switch
 - Dial Pulsing
 - Ground Start
 - Ringing Injection
- Instrumentation
 - Multiplexers
 - Data Acquisition
 - Electronic Switching
 - I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment-Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Description

XBB170 is a dual 350V, 100mA, 50 Ω , normally closed (1-Form-B) relay that features low on-resistance. Using optically coupled MOSFET technology, it provides 3750V_{rms} of input to output isolation.

Its optically coupled outputs, which use the patented OptoMOS architecture, are controlled by a highly efficient GaAIAs infrared LED.

Dual single-pole OptoMOS relays provide a more compact design solution than discrete single-pole relays in a variety of applications. The dual relay configuration saves board space by incorporating both relays in a single 8-pin package.

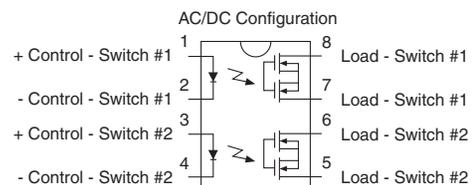
Approvals

- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1175739
- EN/IEC 60950-1 Compliant

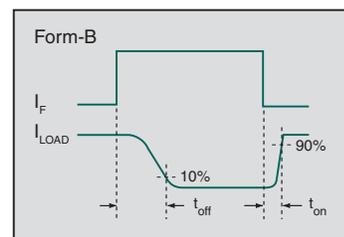
Ordering Information

| Part # | Description |
|-----------|---------------------------------|
| XBB170 | 8-Pin DIP (50/Tube) |
| XBB170P | 8-Pin Flatpack (50/Tube) |
| XBB170PTR | 8-Pin Flatpack (1000/Reel) |
| XBB170S | 8-Pin Surface Mount (50/Tube) |
| XBB170STR | 8-Pin Surface Mount (1000/Reel) |

Pin Configuration



Switching Characteristics of Normally Closed Devices



Absolute Maximum Ratings @ 25°C

| Parameter | Ratings | Units |
|--------------------------------------|-------------|------------------|
| Blocking Voltage | 350 | V _P |
| Reverse Input Voltage | 5 | V |
| Input Control Current | 50 | mA |
| Peak (10ms) | 1 | A |
| Input Power Dissipation ¹ | 150 | mW |
| Total Power Dissipation ² | 800 | mW |
| Isolation Voltage, Input to Output | 3750 | V _{rms} |
| Operational Temperature | -40 to +85 | °C |
| Storage Temperature | -40 to +125 | °C |

¹ Derate linearly 1.33 mW / °C

² Derate linearly 6.67 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

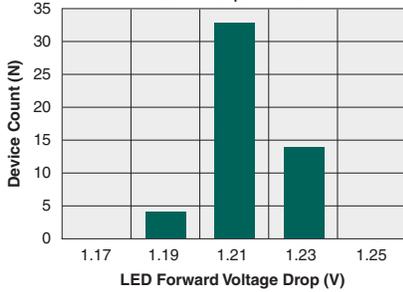
Electrical Characteristics @ 25°C

| Parameter | Conditions | Symbol | Min | Typ | Max | Units |
|--|--|-------------------|-----|-----|------|--------------------------------------|
| Output Characteristics | | | | | | |
| Load Current | | | | | | |
| Continuous, AC/DC Configuration ¹ | - | I _L | - | - | 100 | mA _{rms} / mA _{DC} |
| Peak | t=10ms | I _{LPK} | - | - | ±350 | mA _P |
| On-Resistance, AC/DC Configuration | I _L =120mA | R _{ON} | - | 33 | 50 | Ω |
| Off-State Leakage Current | V _L =350V _P | I _{LEAK} | - | - | 1 | μA |
| Switching Speeds | | | | | | |
| Turn-On | I _F =5mA, V _L =10V | t _{on} | - | - | 5 | ms |
| Turn-Off | | t _{off} | - | - | 5 | |
| Output Capacitance | V _L =50V, f=1MHz | C _{OUT} | - | 25 | - | pF |
| Input Characteristics | | | | | | |
| Input Control Current to Activate | I _L =120mA | I _F | - | - | 5 | mA |
| Input Control Current to Deactivate | - | I _F | 0.4 | 0.7 | - | mA |
| Input Voltage Drop | I _F =5mA | V _F | 0.9 | 1.2 | 1.4 | V |
| Reverse Input Current | V _R =5V | I _R | - | - | 10 | μA |
| Common Characteristics | | | | | | |
| Input to Output Capacitance | - | C _{I/O} | - | 3 | - | pF |

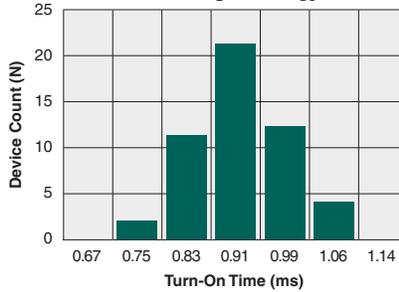
¹ If both poles operate simultaneously, then the load current must be derated so as not to exceed the package power dissipation value.

PERFORMANCE DATA @25°C (Unless Otherwise Noted)*

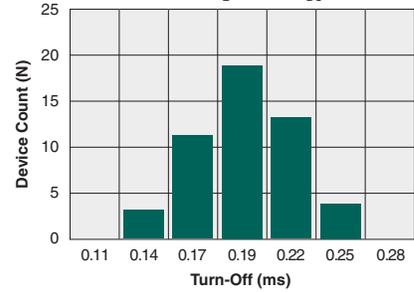
Typical LED Forward Voltage Drop
(N=50, $I_F=5mA$)



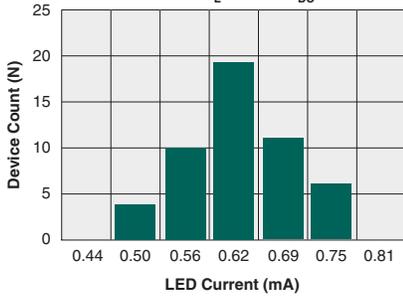
Typical Turn-On Time
(N=50, $I_L=100mA_{DC}$)



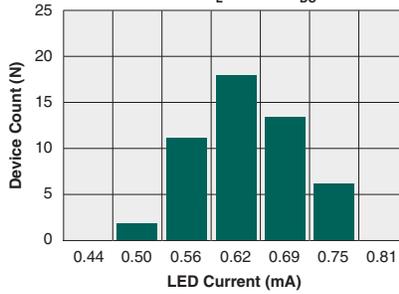
Typical Turn-Off Time
(N=50, $I_L=100mA_{DC}$)



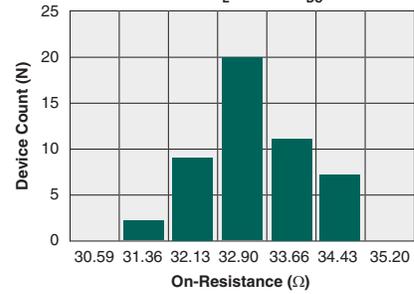
Typical I_F for Switch Operation
(N=50, $I_L=100mA_{DC}$)



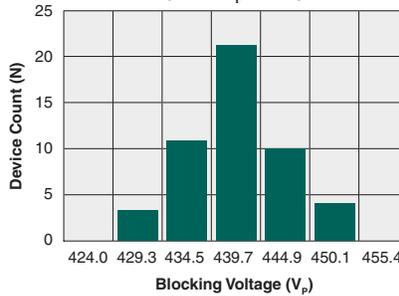
Typical I_F for Switch Dropout
(N=50, $I_L=100mA_{DC}$)



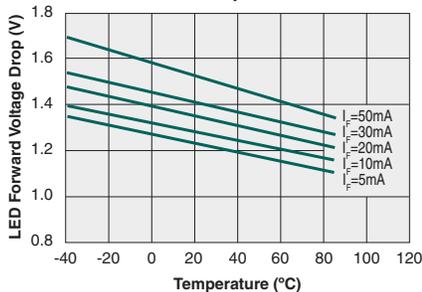
Typical On-Resistance Distribution
(N=50, $I_L=100mA_{DC}$)



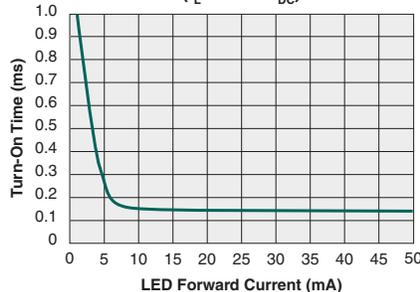
Typical Blocking Voltage Distribution
(N=50, $I_F=5mA$)



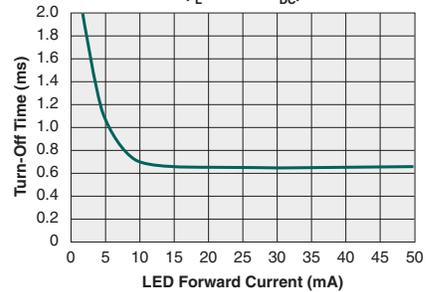
Typical LED Forward Voltage Drop vs. Temperature



Typical Turn-On Time vs. LED Forward Current
($I_L=100mA_{DC}$)

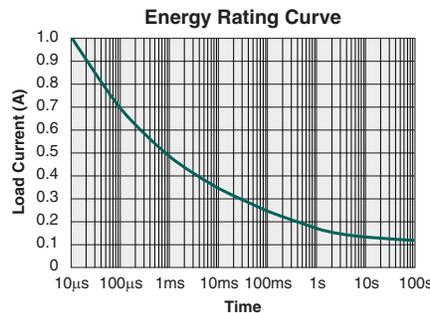
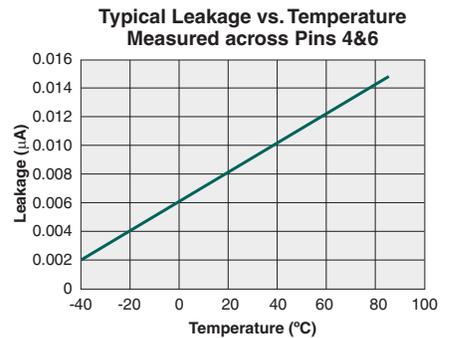
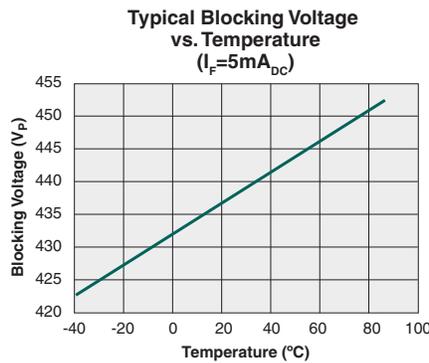
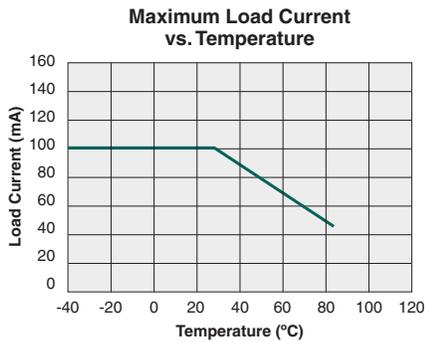
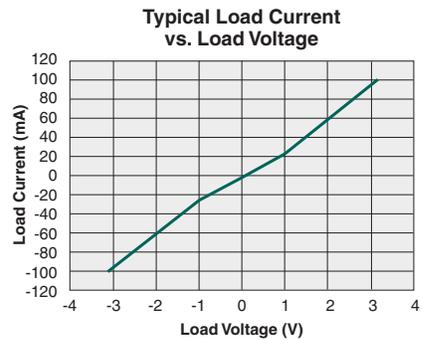
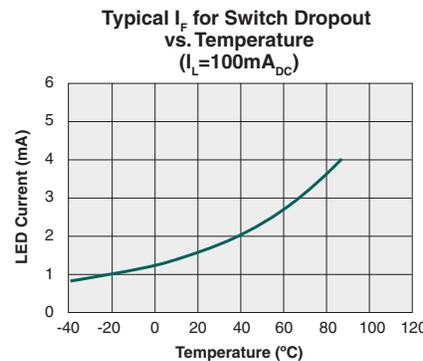
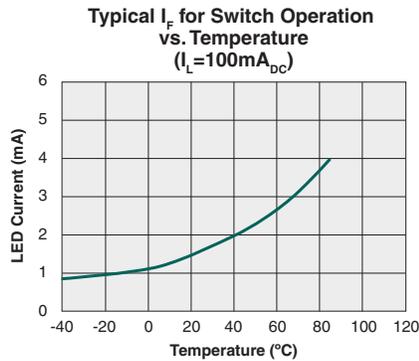
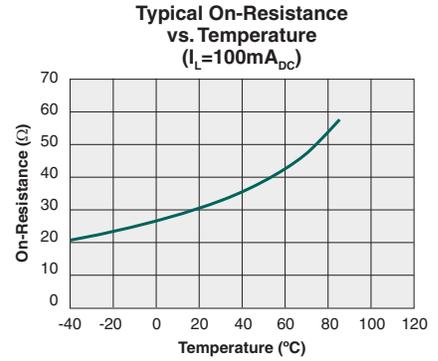
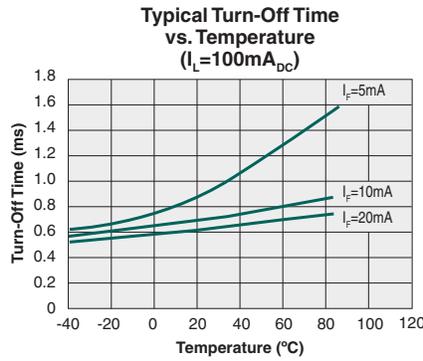
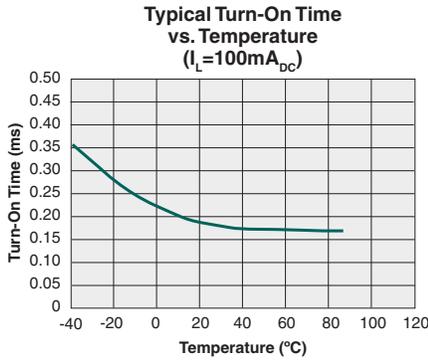


Typical Turn-Off Time vs. LED Forward Current
($I_L=100mA_{DC}$)



*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

PERFORMANCE DATA @25°C (Unless Otherwise Noted)*



*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

| Device | Moisture Sensitivity Level (MSL) Rating |
|----------------------------|---|
| XBB170 / XBB170S / XBB170P | MSL 1 |

ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

| Device | Maximum Temperature x Time |
|------------------|----------------------------|
| XBB170 / XBB170S | 250°C for 30 seconds |
| XBB170P | 260°C for 30 seconds |

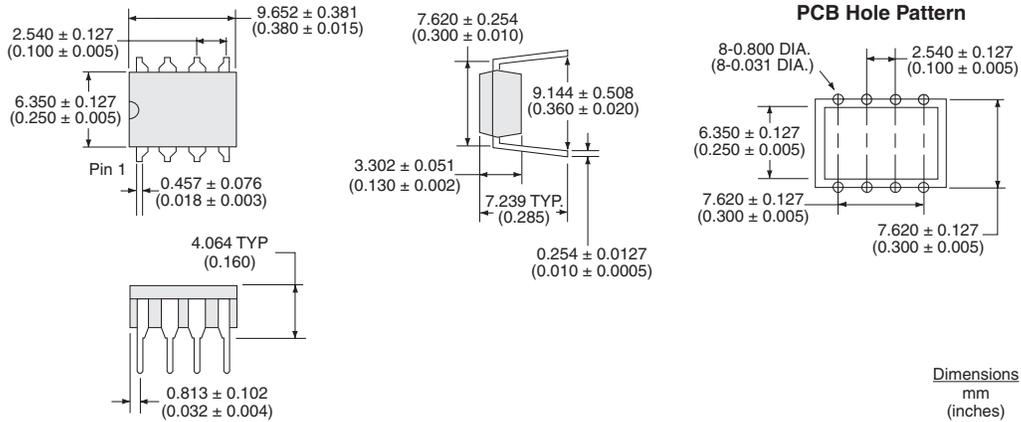
Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

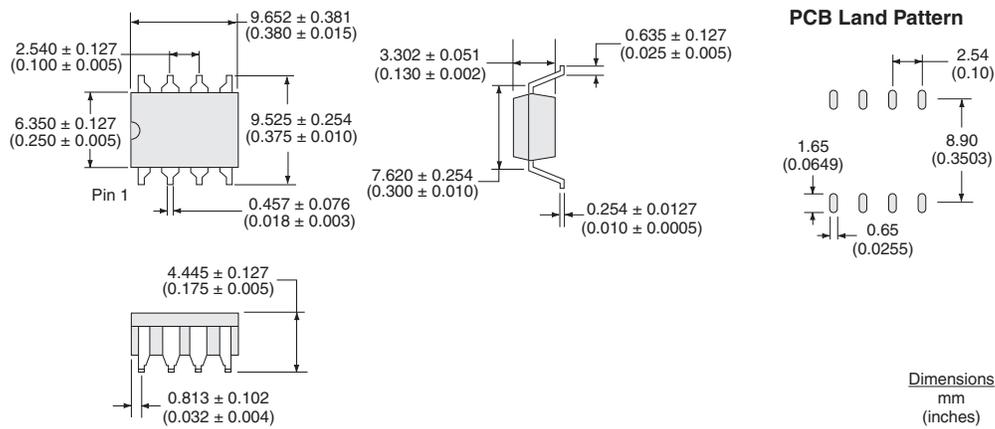


Mechanical Dimensions

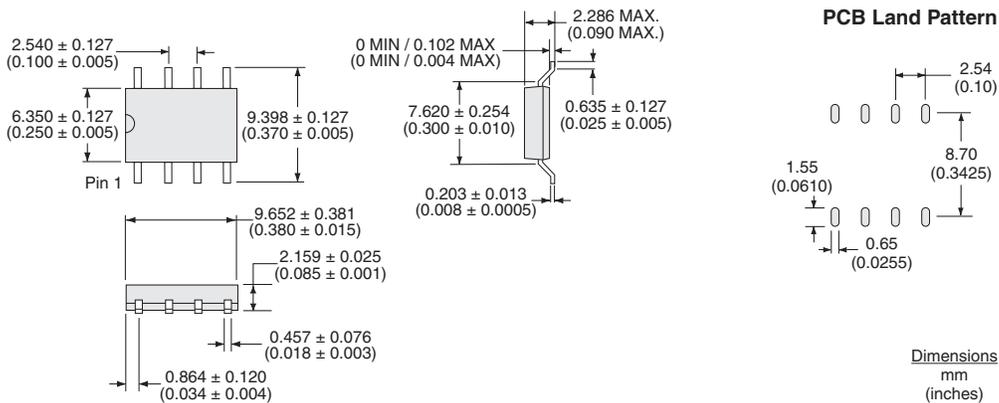
XBB170



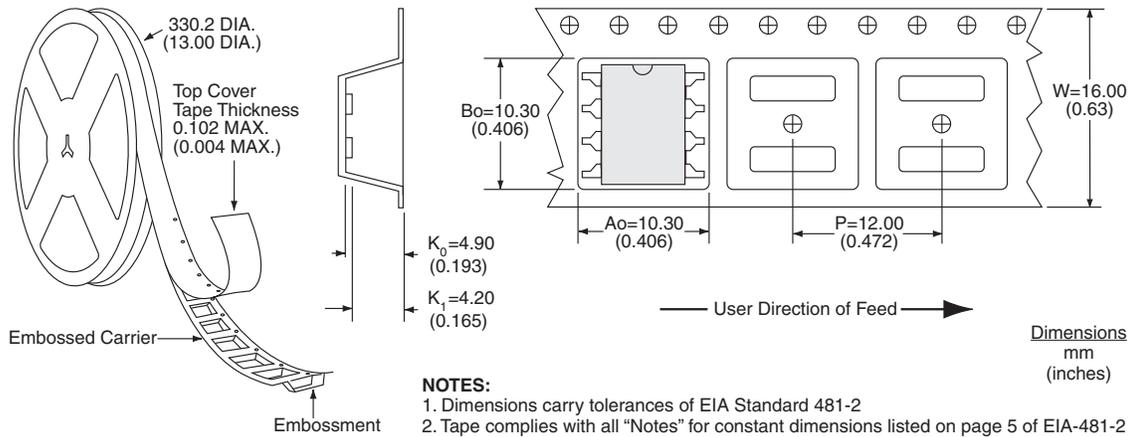
XBB170S



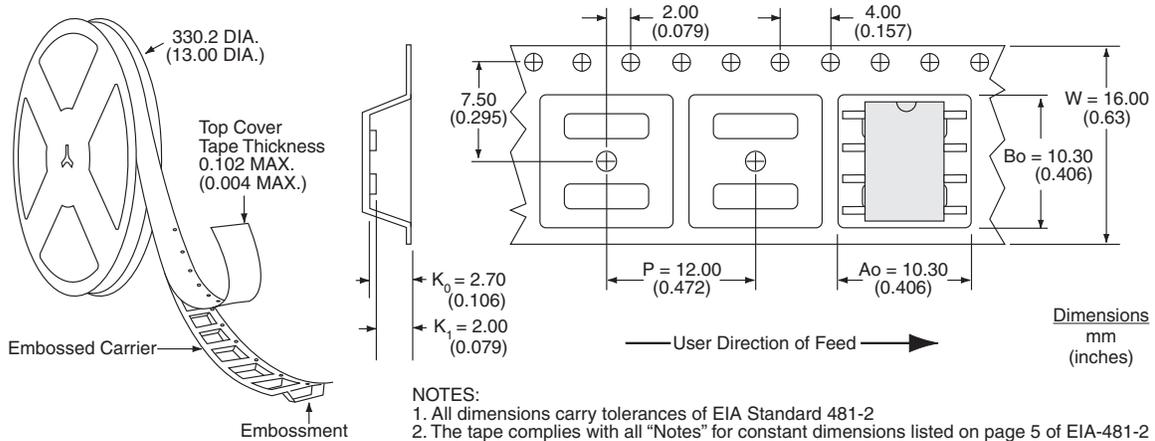
XBB170P



XBB170STR Tape & Reel



XBB170PTR Tape & Reel



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